



Product End-of-Life Disassembly Instructions

Product Category: Workstations

Marketing Name / Model
 [List multiple models if applicable.]

HP xw8600 Workstation

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
 1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm Two in the power supply, one graphics card, and one system board. (Additional cards may be present depending on the configuration.)	4
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	None
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	None
Cathode Ray Tubes (CRT)		None
Capacitors / condensers (Containing PCB/PCT)		None
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	Eleven attached to the power supply boards.	11
External electrical cables and cords		1
Gas Discharge Lamps		None
Plastics containing Brominated Flame Retardants		None
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	None
Components and waste containing asbestos		None
Components, parts and materials containing refractory ceramic fibers		None
Components, parts and materials containing radioactive substances		None

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.


Tool Description	Tool Size (if applicable)
Assorted Torx drivers, screwdrivers and a diagonal cutter	

3.0 Product Disassembly Process

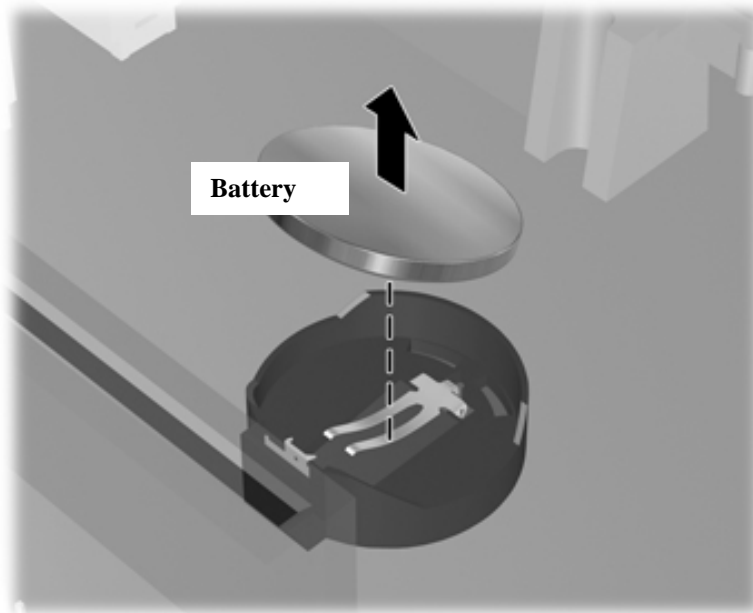
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

(See instructions below in sections 3.2 and 3.3.)

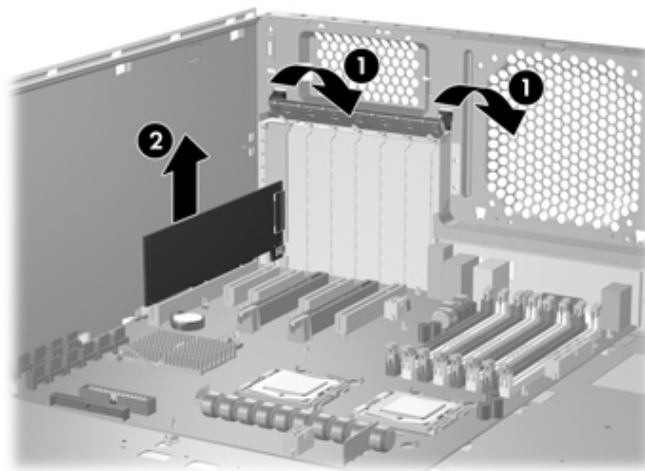
3.2 Workstation Disassembly Procedures

1.	Remove/disengage any security devices that prohibit opening the workstation.
2.	Disconnect the power cord from the electrical outlet and then from the workstation.
3.	Disconnect all peripheral device cables from the workstation.
4.	<p>Remove the access panel. Pull up on the handle and rotate the cover off the chassis as shown in the following figure.</p> 
5.	Disconnect all internal cables from system board, power supply, and other components.

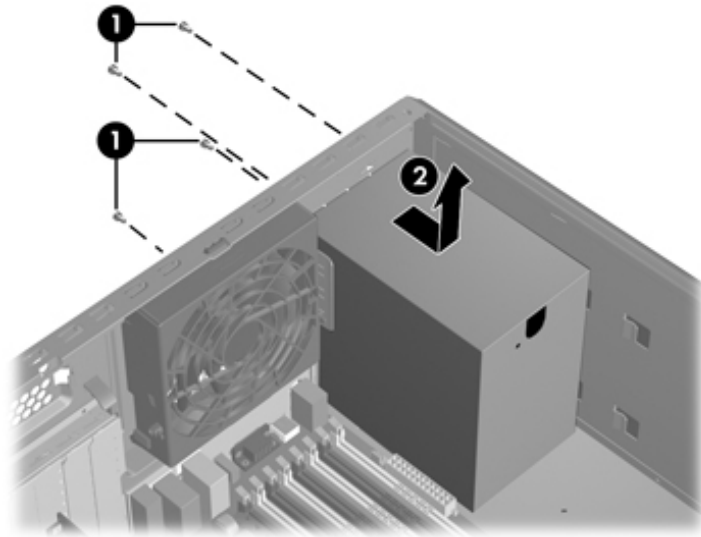
6. Remove the system battery. Press on the release tab of the battery holder. Rotate the battery beyond the latch and lift it straight up.



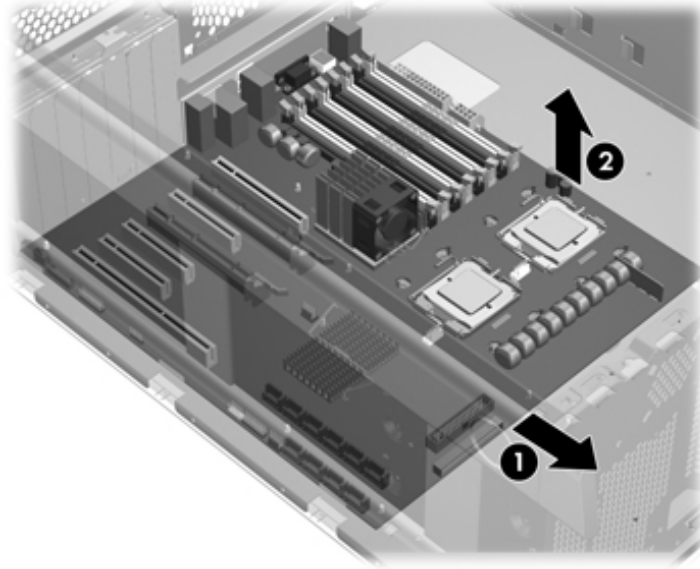
7. Remove the graphics card and any other expansion cards. Open the PCI card retention clamp by pressing the retention clamp levers down to unsnap, and then rotating them up (1) as shown in the following figure. Lift the PCI card out of the chassis (2).



8. Remove the power supply from the chassis. Disconnect or cut electrical connections to the power supply. Remove the four screws securing the power supply to the workstation chassis (1). Slide the power supply toward the front of the chassis, and then lift it out of the chassis (2).



9. Remove the system board. To disengage the metal mounting standoffs from the chassis (1), slide the system board forward. Lift the system board out of the chassis (2).



10. Dispose of all removed components according to regulatory requirements.

3.3 Power Supply Disassembly Procedures

1. Refer to the Items Requiring Selective Treatment table to identify all components to be removed.

2. Cut the cable tie at the rear of the unit.



3. Remove the four power supply chassis screws—two from each side.



4. Slide the chassis housing from the power supply unit.



5. Remove the four screws from the corners of the large PCB card. Remove the large PCB card from the unit.



6. Ensure that all capacitors are safely discharged. Use a diagonal cutter to remove the desired components from both PCB cards. (Note that some components may need to be unsoldered if a diagonal cutter does not fit between the component and the PCB card.)



7. Dispose of all removed components according to regulatory requirements.